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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Application Serial No. Filed Concurrently Herewith	
Filing Date Filed Concurrently Herewith	
Inventor Keiji Jono et al.	
Assignee Micron Technology, Inc. and KMT Semiconductor, LTD	
Group Art Unit	
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Attorney's Docket No	
Title: Methods of Forming an Isolation Trench in a Semiconductor, Methods of Forming an Isolation Trench in a Surface of a Silicon Wafer, Methods of Forming an Isolation Trench-Isolated Transistor, Trench-Isolated Transistor,	١,
Forming an Isolation Trench in a Surface of a Silicon Wafer, Methods of Illing	H
Forming an Isolation Trench-Isolated Transistor, Trench-Isolated Transistor,	
Trench Isolation Structures Formed in a Semiconductor, Memory Cells and	
DRAMS	

INFORMATION DISCLOSURE STATEMENT

References - - See attached Form PTO-1449

The citations listed, copies attached, may be material to the examination of the subject application and are therefore submitted in compliance with the duty of disclosure defined in 37 CFR §1.56. The Examiner is requested to make these citations of official record in this application. No admission is made regarding whether all the submitted references are prior art.

The listed references are discussed in the specification under the heading "Background of the Invention".

The materials cited are presented to assist in and expedite examination of this application. The present invention is considered to be patentable over the cited materials. Expeditious examination and allowance of this application as a patent are therefore urged in order that the public may benefit from the disclosure and commercialization of the invention.

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Citation of these references is respectfully requested.

Respectfully submitted,

Dated: Aug3/12000

Attorney:

Frederick M. Fliegel, Ph.D.

Reg. No.: 36,138

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	AR	Shallow Trench Isolation Characteristics with High-Density-Plasma Chemical Vapor Deposition Gap-Fill Oxide for Deep-Submicron CMOS								
		Technologies, Se	eung-Ho Lee et	al., Jpn. J. Ap	ppl. Phys. Vol. 37 (19	98), pp. 1222-1227.				
	AS	Impact of Shallow	Trench Isolation	n on Reliability	of Buried- and Surfa	nce-Chanel sub-µm PFE	7; William T	onti et al., 19	95 IEEE. pp.	24-29.
	AT	Subbreakdown Dra	Subbreakdown Drain Leakage Current in MOSFET, J. Chen et al., 1987 IEEE, pp.515-517.							
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APPLICANT Keiji Jono et al.	
FILING DATE	GROUP

U.S. PATENT DOCUMENTS Filing Date Class Subclass Document Number Date Name *Examiner If Appropriate Initial AA AB AC AD ΑE AF AGAH ΑI AJ ΑK FOREIGN PATENT DOCUMENTS Date Country Class Subclass Translation Document Number Yes No ΑL AM AN AO AP OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) Shallow Trench Isolation for advanced ULSI CMOS Technologies, M. Nandakumar et al, Silicon Technology Development, AR Kilby Center, Texas Instruments, Undated, 4 pages. AS ΑT DATE CONSIDERED **EXAMINER**

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.